

L Number	Hits	Search Text	DB	Time stamp
1	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:19
2	88792	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:21
3	4591	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)) and (test or testing or tested)same (wafer or chip or semiconductor or ciecuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:24
4	449	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)) and (test or testing or tested)same (wafer or chip or semiconductor or ciecuit)) and (liquid adjl crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:26
5	325	((((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)) and (test or testing or tested)same (wafer or chip or semiconductor or ciecuit)) and (liquid adjl crystal)) and (laser or beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:28
-	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:18
-	53138	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:19
-	9052	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:21
-	1115	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adjl crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:22
-	267	((((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adjl crystal)) and (image and (defect or flaw))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:24
-	204	((((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adjl crystal)) and (image and (defect or flaw))) and (substrate with (removal or removed or removing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:26

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1	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:19
2	88792	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:21
3	4591	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)) and (test or testing or tested)same (wafer or chip or semiconductor or cicuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:24
4	449	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)) and (test or testing or tested)same (wafer or chip or semiconductor or cicuit)) and (liquid adj1 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:26
5	325	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperature)) and (test or testing or tested)same (wafer or chip or semiconductor or cicuit)) and (liquid adj1 crystal)) and (laser or beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:51
6	2	5576630.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/04 09:51
-	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:18
-	53138	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:19
-	9052	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:21
-	1115	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:22
-	267	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:24

-	204	((((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested) and (semiconductor or circuit or chip)) and (liquid adjl crystal)) and (image and (defect or flaw))) and (substrate with (removal or removed or removing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:26
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-	362	324/752	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/26 12:04
-	97872	250/\$.ccls. or 324/751 or 324/752	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/26 12:04
-	19043	(laser same (chip or die or circuit) and heat)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/27 10:30
-	936	(250/\$.ccls. or 324/751 or 324/752) and ((laser same (chip or die or circuit) and heat))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/26 12:07
-	442	((250/\$.ccls. or 324/751 or 324/752) and ((laser same (chip or die or circuit) and heat))) and (defect or error or flaw)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/26 12:07
-	73	((((250/\$.ccls. or 324/751 or 324/752) and ((laser same (chip or die or circuit) and heat))) and (defect or error or flaw)) and (liquid adj2 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/26 12:08